

Amendments to the Claims

This listing of claims will replace all prior listings of claims in the application.

Listing of Claims

1.-11. (Canceled)

12. (Previously Presented) A method for manufacturing a multi-layer ceramic electronic part comprising the steps of:

preparing an unbaked laminated body comprising a ceramic layer and internal electrodes laminated on one another;

applying and drying a conductor paste, into which is added a material common with a ceramic forming the ceramic layer of the laminated body, on edge portions of the unbaked laminated body;

forming external electrodes in contact with the internal electrodes at end surfaces of the laminated body;

baking the laminated body; and

providing ceramic portions which are scattered in a conductor film forming the external electrodes and continuous in a direction of thickness of the conductor film.

13. (Previously Presented) A method for manufacturing a multi-layer ceramic electronic part comprising the steps of:

preparing an unbaked laminated body comprising a ceramic layer and internal electrodes laminated on one another;

applying and drying a conductor paste, into which is added a material common with a ceramic forming the ceramic layer of the laminated body, on edge portions of the unbaked laminated body;

forming external electrodes in contact with the internal electrodes at end surfaces of the laminated body;

baking the laminated body; and forming ceramic portions in the external electrodes that are continuous from an inner surface of a conductor film forming the external electrodes where the conductor film closely contacts with a surface of the laminated body, extending to an outer surface of the external electrodes.

14. (Canceled)

15. (Previously Presented) The method of Claim 12, additionally comprising the step of forming the conductor film of at least one metal selected from the group consisting of Ni, Cu, Ag, Pd and an Ag-Pd alloy.

16. (Previously Presented) The method of Claim 13, additionally comprising the step of forming the conductor film of at least one metal selected from the group consisting of Ni, Cu, Ag, Pd and an Ag-Pd alloy.

17. (Canceled)

18. (Previously Presented) The method of Claim 12, wherein the ceramic comprises barium titanate.

19. (Previously Presented) The method of Claim 13, wherein the ceramic comprises barium titanate.

20. (Canceled)

21. (Currently Amended) The method of Claim 12, wherein the conductor paste contains from 3-40 wt.% to 40% by weight of the common material.

22. (Currently Amended) The method of Claim 13, wherein the conductor paste contains from 3-40 wt.% to 40% by weight of the common material.